US00D504874S

(12) United States Design Patent

Celaya et al.

(10) Patent No.: US D504,874 S
(45) Date of Patent: ** May 10, 2005

(54) **SEMICONDUCTOR DEVICE PACKAGE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/211,046**

(22) Filed: **Aug. 11, 2004**

(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 174/52.1, 174/52.2, 52.4; 257/666, 669, 675, 676, 678, 690, 692, 696, 697, 730, 787; 361/773, 820; 438/64, 65

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Primary Examiner—Stella Reid
Assistant Examiner—Selina Sikder

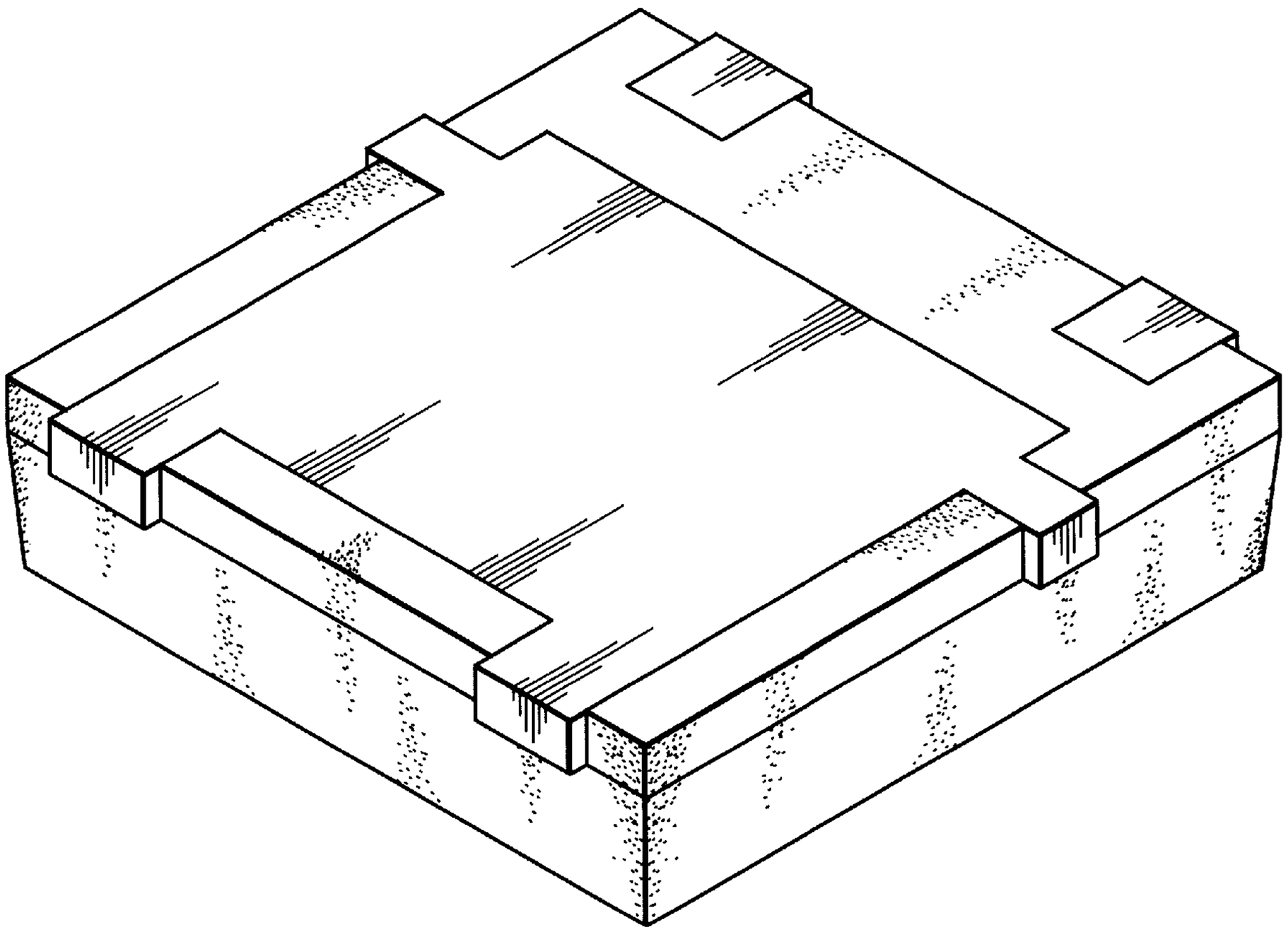
(57) **CLAIM**

We claim the ornamental design for a semiconductor device package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view from the front left side and below the semiconductor device package showing our new design.
FIG. **2** is a top plan view thereof;
FIG. **3** is a bottom plan view thereof; and,
FIG. **4** is an elevational view from the front side thereof.

1 Claim, 3 Drawing Sheets



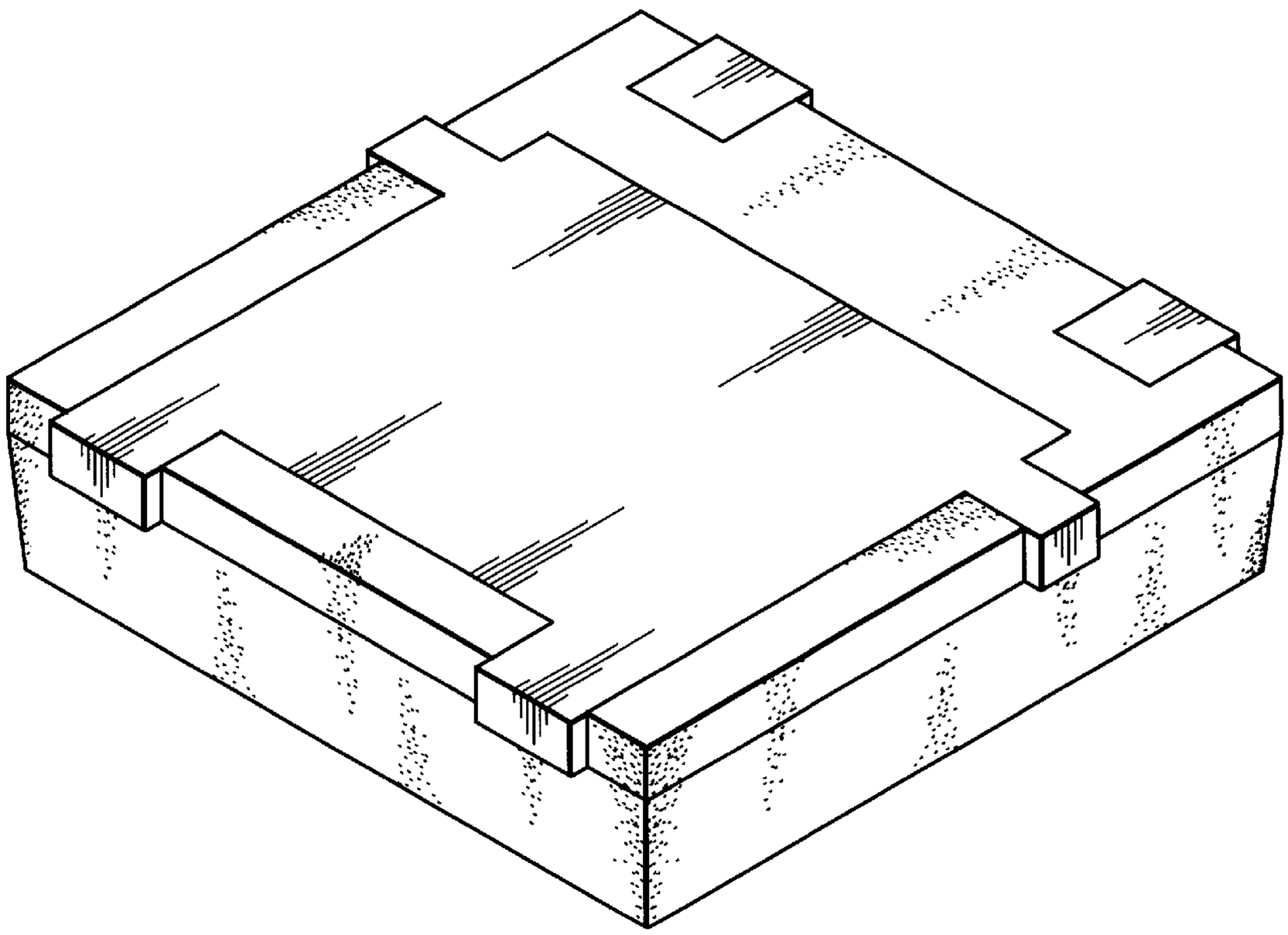


FIG. 1

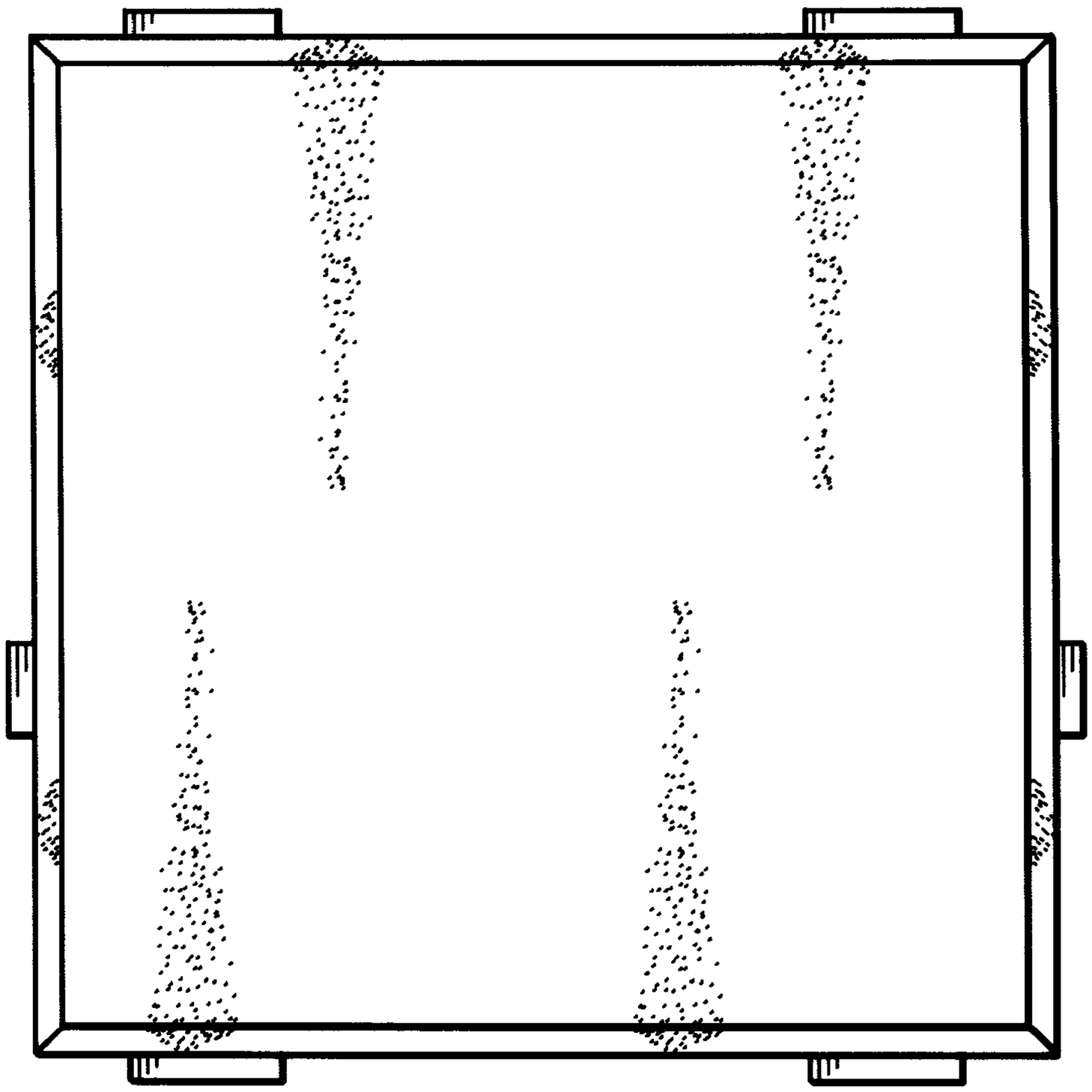


FIG. 2

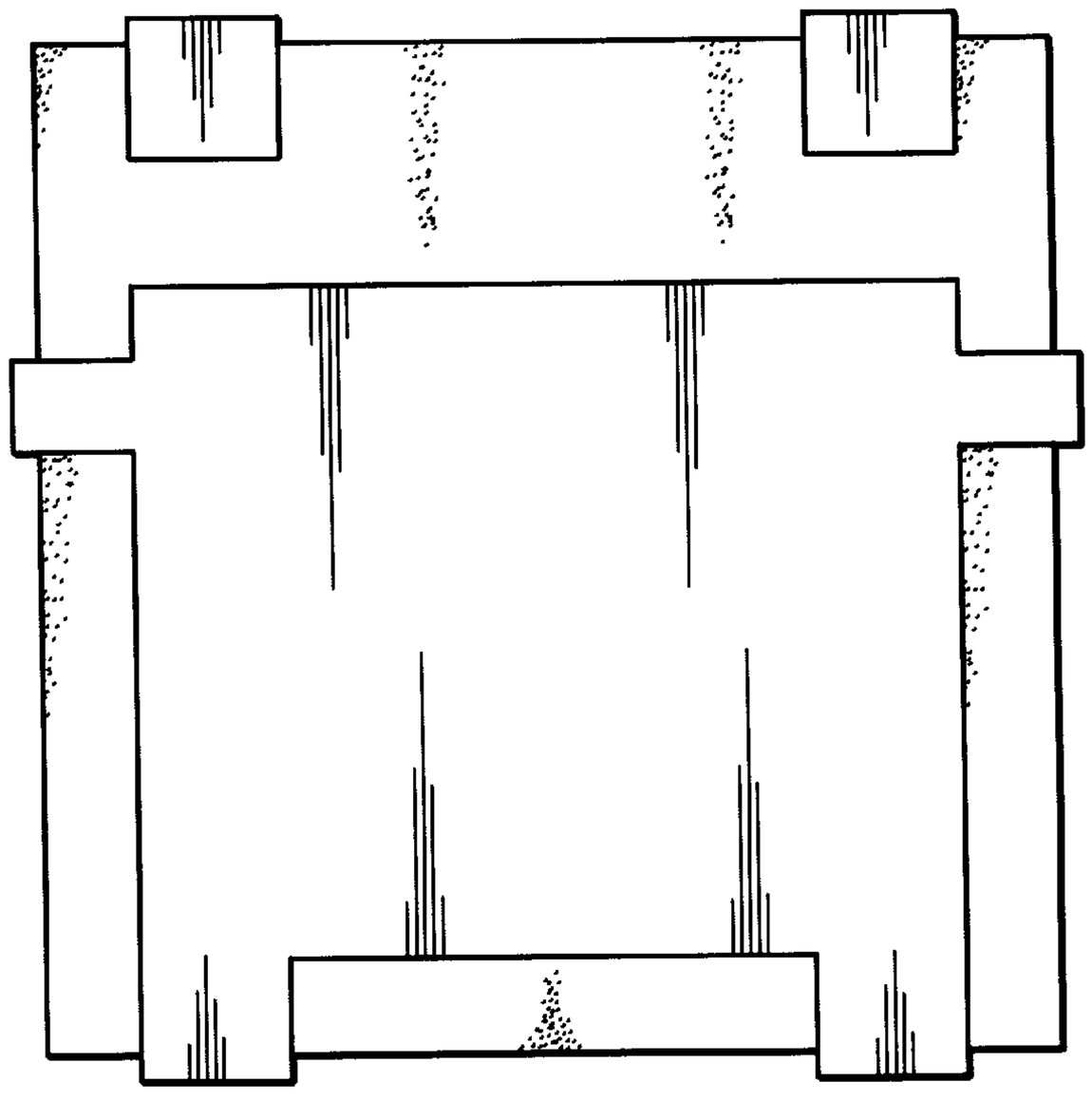


FIG. 3

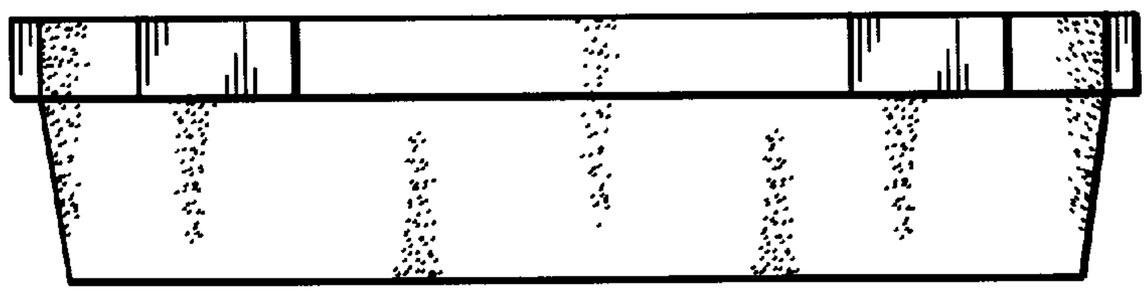


FIG. 4